Abstract

Method for producing a semiconductor device and corresponding semiconductor device

The present invention provides a method for producing a semiconductor device, with the steps of: applying an interconnect level (11, 12) to a semiconductor substrate (10); structuring the interconnect level (12); and applying a solder layer (13) on the structured interconnect level (11, 12) in such a way that the solder layer (13) assumes the structure of the interconnect level (11, 12). The present invention likewise provides such a semiconductor device.

Figure 1

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